

SOT617-28(DD)

HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

22 April 2022

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-01-2021
Manufacturer package code	98ASA01901D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package width	-	5	-	mm
seated height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	



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2 Package outline

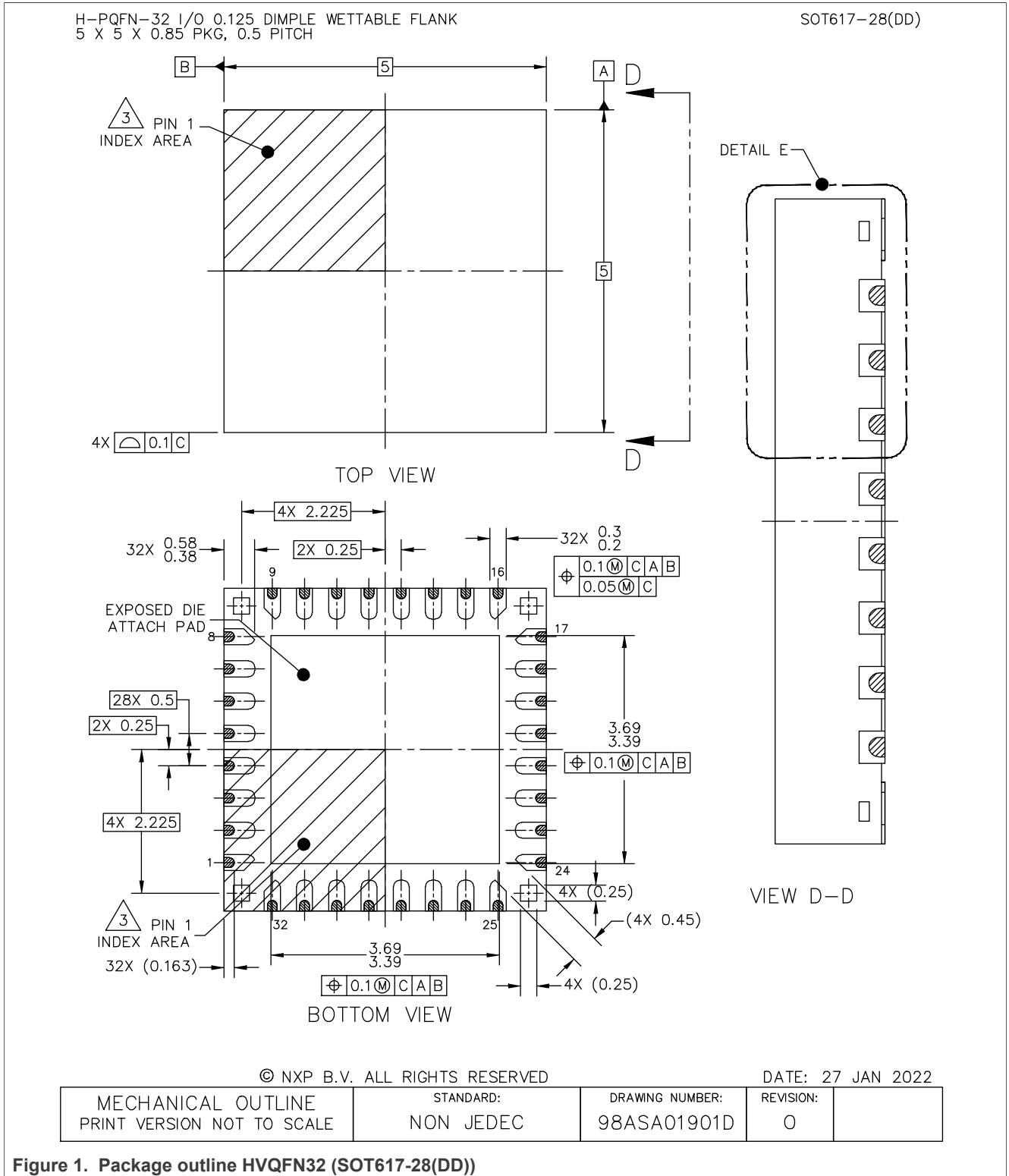
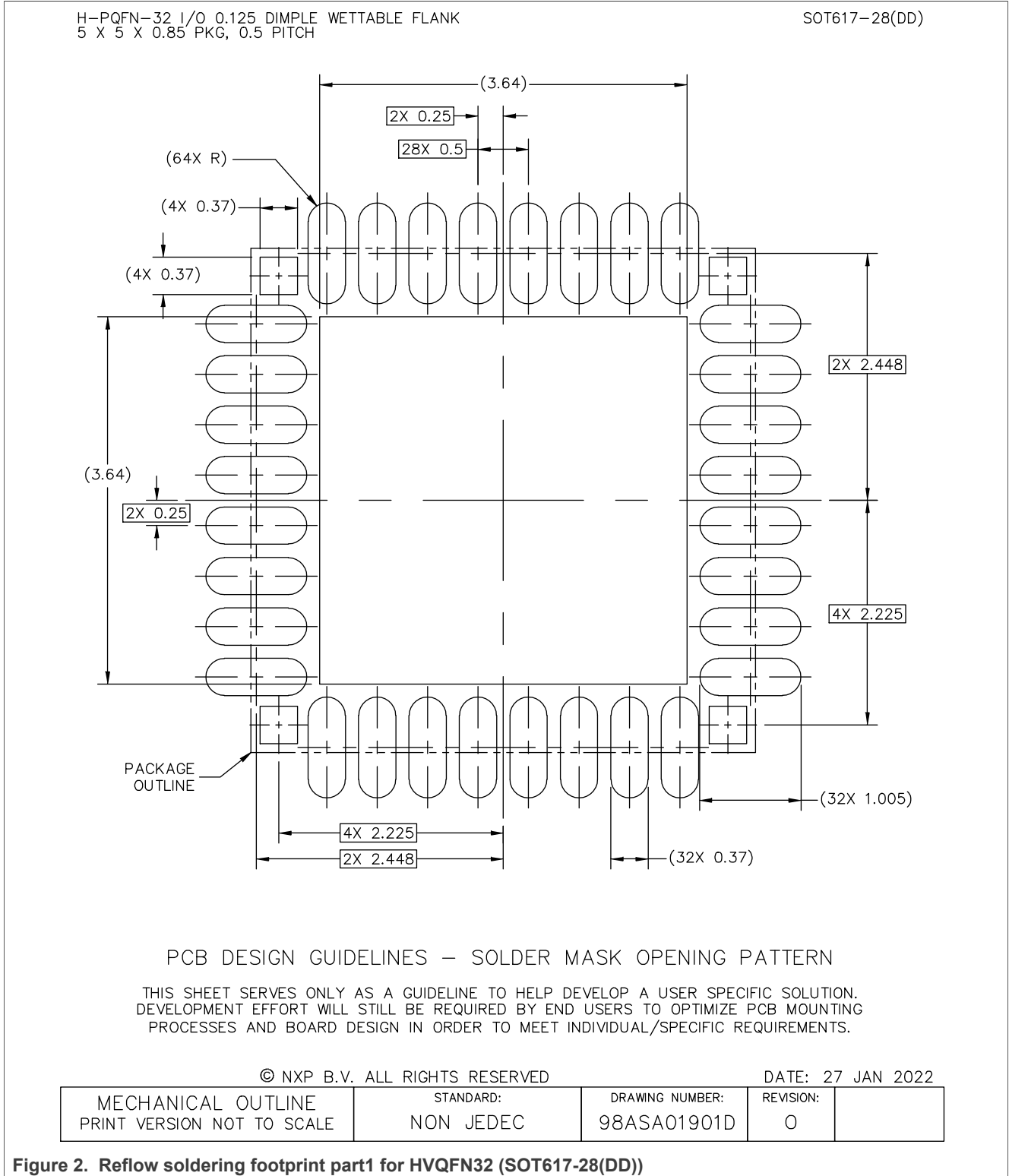


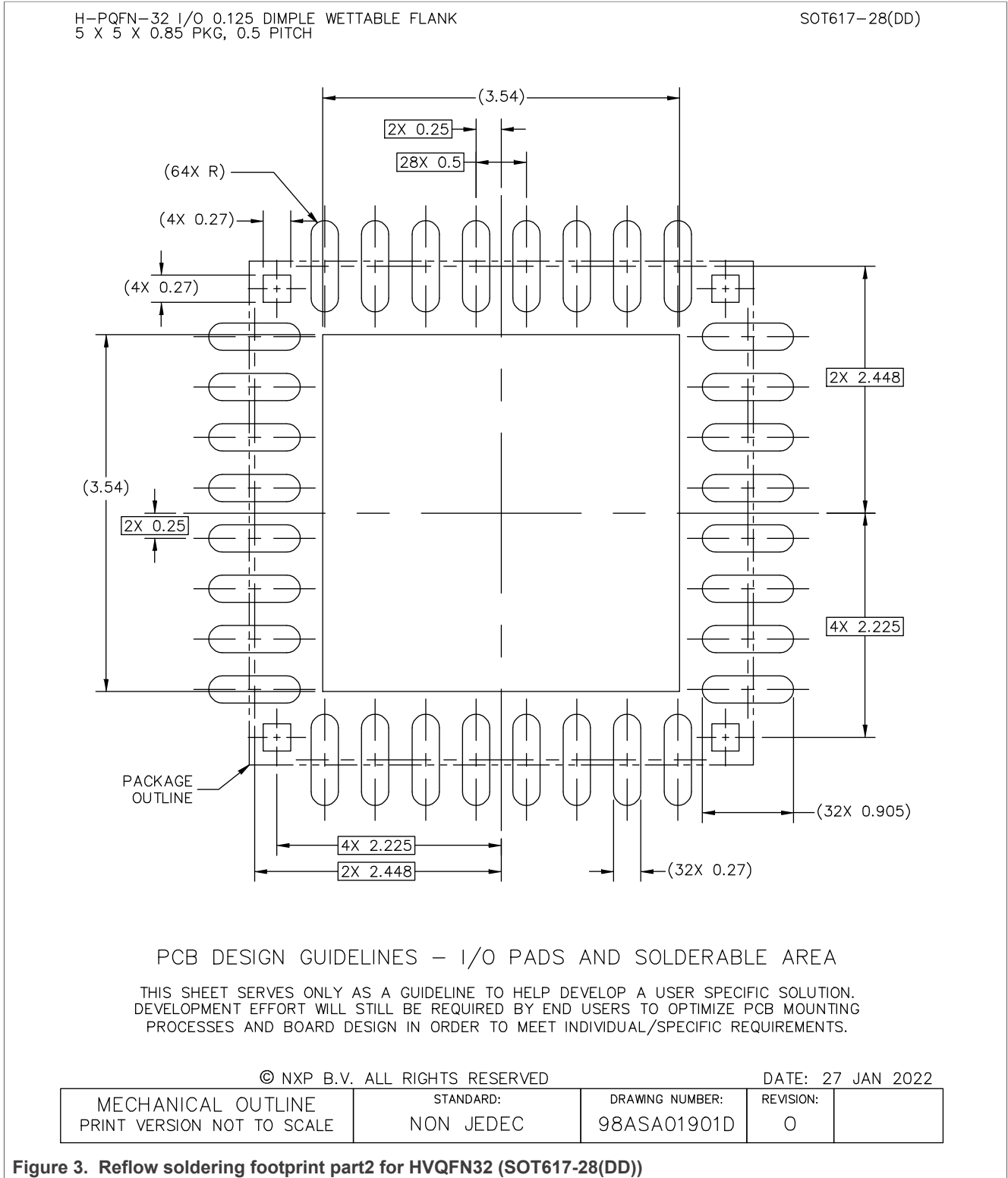
Figure 1. Package outline HVQFN32 (SOT617-28(DD))

HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

3 Soldering



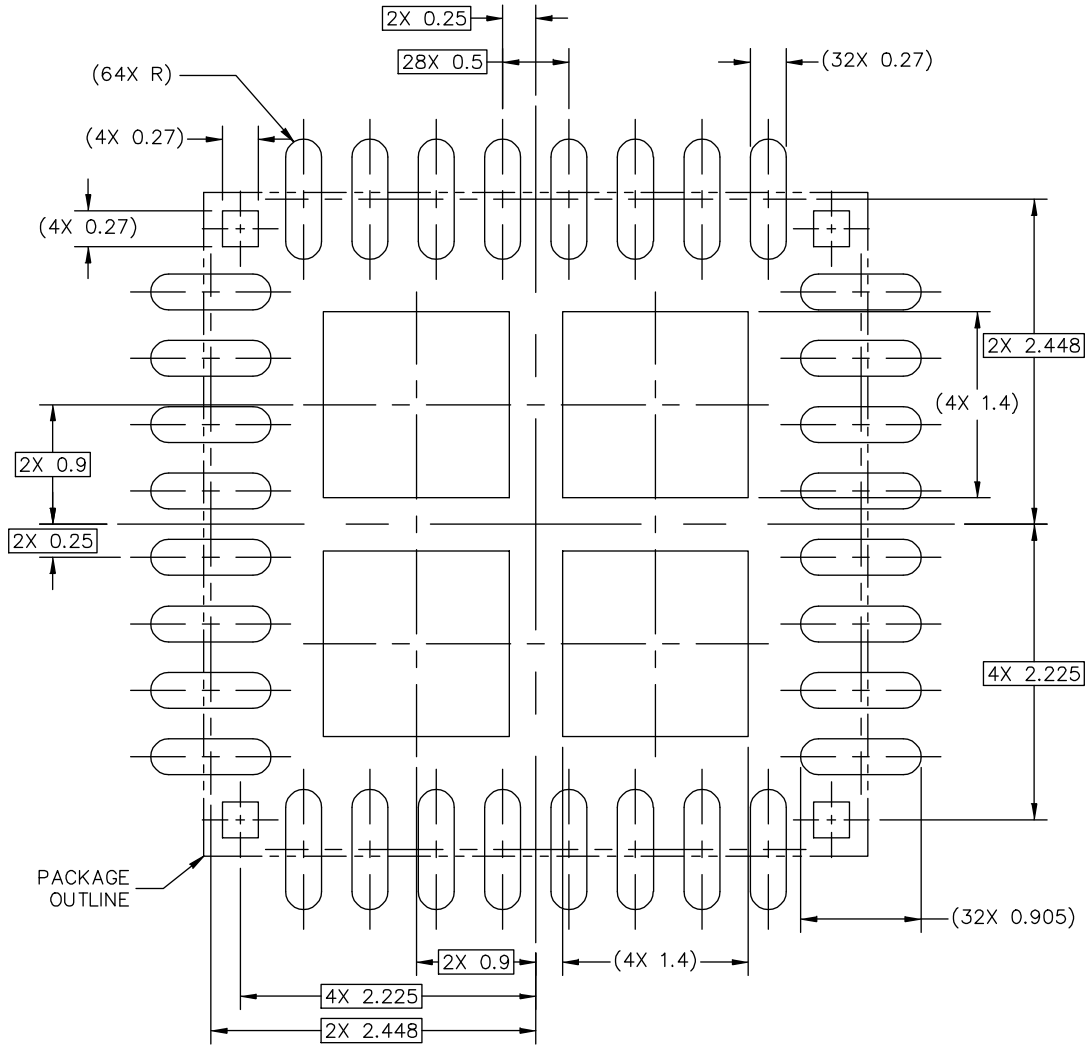
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HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

H-PQFN-32 I/O 0.125 DIMPLE WETTABLE FLANK
5 X 5 X 0.85 PKG, 0.5 PITCH

SOT617-28(DD)



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 27 JAN 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01901D	REVISION: 0
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Figure 4. Reflow soldering footprint part3 for HVQFN32 (SOT617-28(DD))

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5 X 5 X 0.85 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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Figure 5. Package outline note HVQFN32 (SOT617-28(DD))

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